

Abstract Of The Disclosure

5 An RF multilayer circuit board having: a first conductive device in a first plane for providing a first RF signal line; a first reference potential plane in a second plane for providing a reference potential of the first RF signal line; at least one second
10 reference potential plane in a third plane for providing a reference potential of an at least one second RF signal line; at least one second conductive device in a fourth plane for providing a second RF signal line; a plated through hole device for electrically connecting the first and second conductive devices, the first and second reference potential planes each having a recess between them in the area of the
15 plated through hole device; and at least one additional conductive device in the area of the plated through hole device at least between the first and second reference potential planes and bonding them in order to provide a waveguiding channel around the plated through hole device.